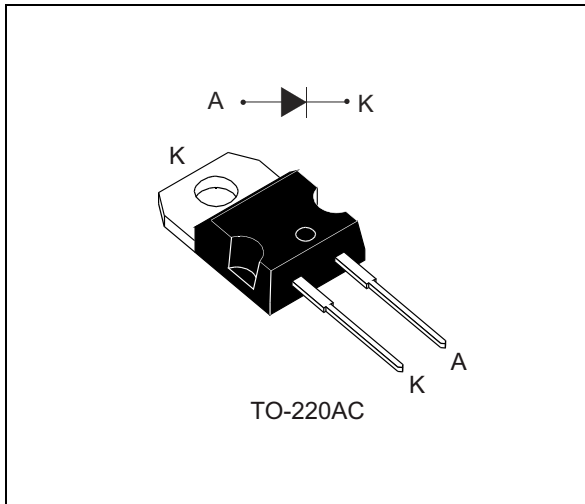


## 650 V power Schottky silicon carbide diode

Datasheet - production data



### Description

The SiC diode is an ultrahigh performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide band gap material allows the design of a Schottky diode structure with a 650 V rating. Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC applications, ST SiC diode will boost the performance in hard switching conditions. Its high forward surge capability ensures more margin during transient phases.

### Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- High forward surge capability

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	4 A
$V_{RRM}$	650 V
$T_j$ (max)	175 °C

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		650	V
$I_{F(RMS)}$	Forward rms current		11	A
$I_{F(AV)}$	Average forward current	$T_C = 140\text{ °C}^{(1)}$ , DC	4	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal, $T_C = 25\text{ °C}$	34	A
		$t_p = 10\text{ ms}$ sinusoidal, $T_C = 125\text{ °C}$	31	
		$t_p = 10\text{ }\mu\text{s}$ square, $T_C = 25\text{ °C}$	290	
$I_{FRM}$	Repetitive peak forward current	$T_C = 140\text{ °C}^{(1)}$ , $T_j = 175\text{ °C}$ , $\delta = 0.1$	17	A
$T_{stg}$	Storage temperature range		-55 to +175	°C
$T_j$	Operating junction temperature <sup>(2)</sup>		-40 to +175	°C

1. Value based on  $R_{th(j-c)}$  (max)
2.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter	Value		Unit
		Typ.	Max.	
$R_{th(j-c)}$	Junction to case	2.5	3.2	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit	
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	2	30	$\mu\text{A}$
		$T_j = 150\text{ °C}$		-	30	150	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 4\text{ A}$	-	1.56	1.75	V
		$T_j = 150\text{ °C}$		-	1.98	2.5	

1.  $t_p = 10\text{ ms}$ ,  $\delta < 2\%$
2.  $t_p = 500\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:

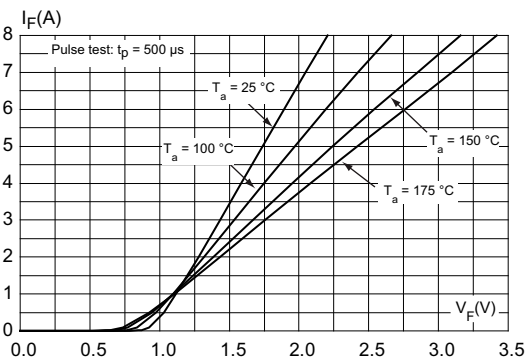
$$P = 1.35 \times I_{F(AV)} + 0.3 \times I_{F(RMS)}^2$$

**Table 5. Dynamic electrical characteristics**

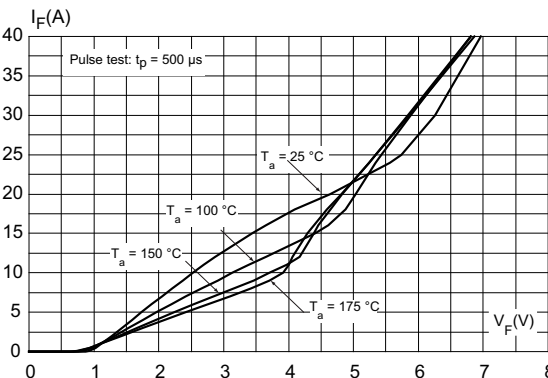
Symbol	Parameter	Test conditions	Typ.	Unit
$Q_{cj}^{(1)}$	Total capacitive charge	$V_R = 400\text{ V}$	7.3	nC
$C_j$	Total capacitance	$V_R = 0\text{ V}$ , $T_C = 25\text{ °C}$ , $F = 1\text{ MHz}$	170	pF
		$V_R = 300\text{ V}$ , $T_C = 25\text{ °C}$ , $F = 1\text{ MHz}$	19	

1. Most accurate value for the capacitive charge:  $Q_{cj} = \int_0^{V_{out}} c_j(V_R).dV_R$

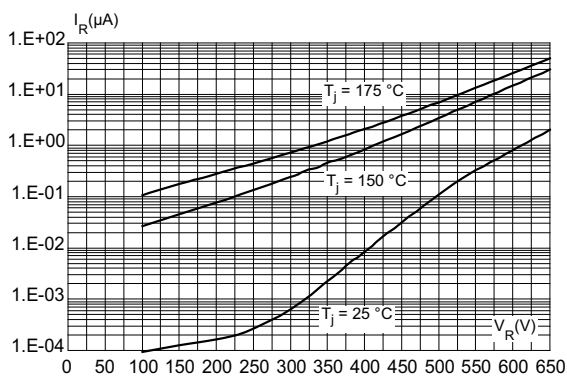
**Figure 1. Forward voltage drop versus forward current (typical values, low level)**



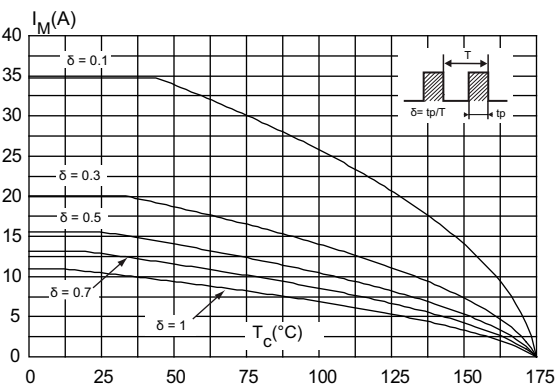
**Figure 2. Forward voltage drop versus forward current (typical values, high level)**



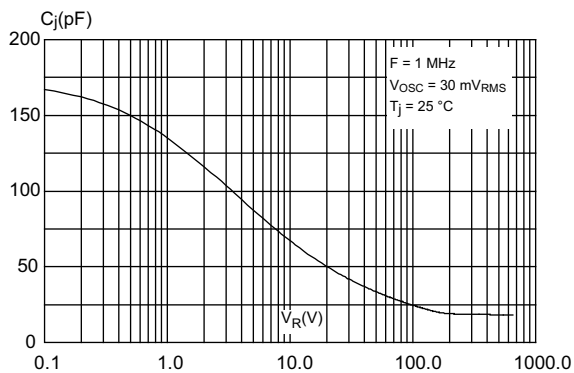
**Figure 3. Reverse leakage current versus reverse voltage applied (typical values)**



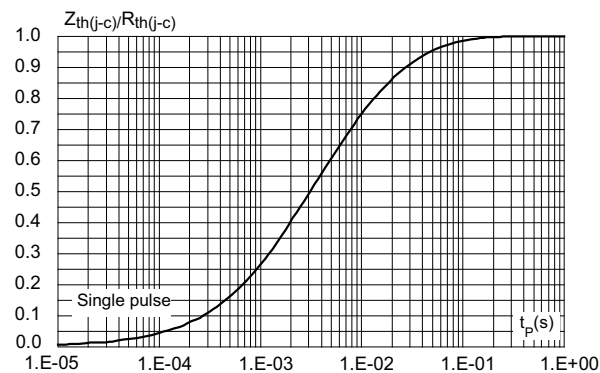
**Figure 4. Peak forward current versus case temperature**



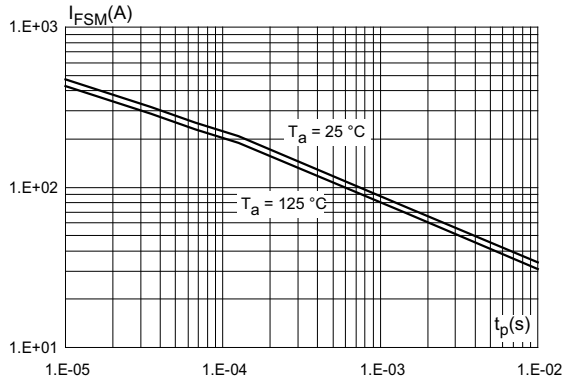
**Figure 5. Junction capacitance versus reverse voltage applied (typical values)**



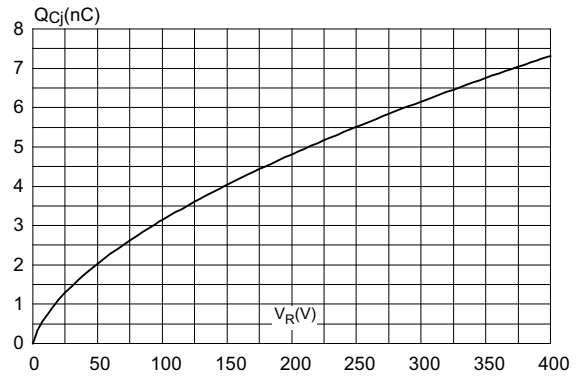
**Figure 6. Relative variation of thermal impedance junction to case versus pulse duration**



**Figure 7. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)**



**Figure 8. Total capacitive charges versus reverse voltage applied (typical values)**



## 2 Package information

- Epoxy meets UL94, V0
- Recommended torque value (TO-220AC): 0.55 N·m
- Maximum torque value: 0.7 N·m for TO-220AC
- Cooling method: conduction (C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

### 2.1 TO-220AC package information

Figure 9. TO-220AC package outline

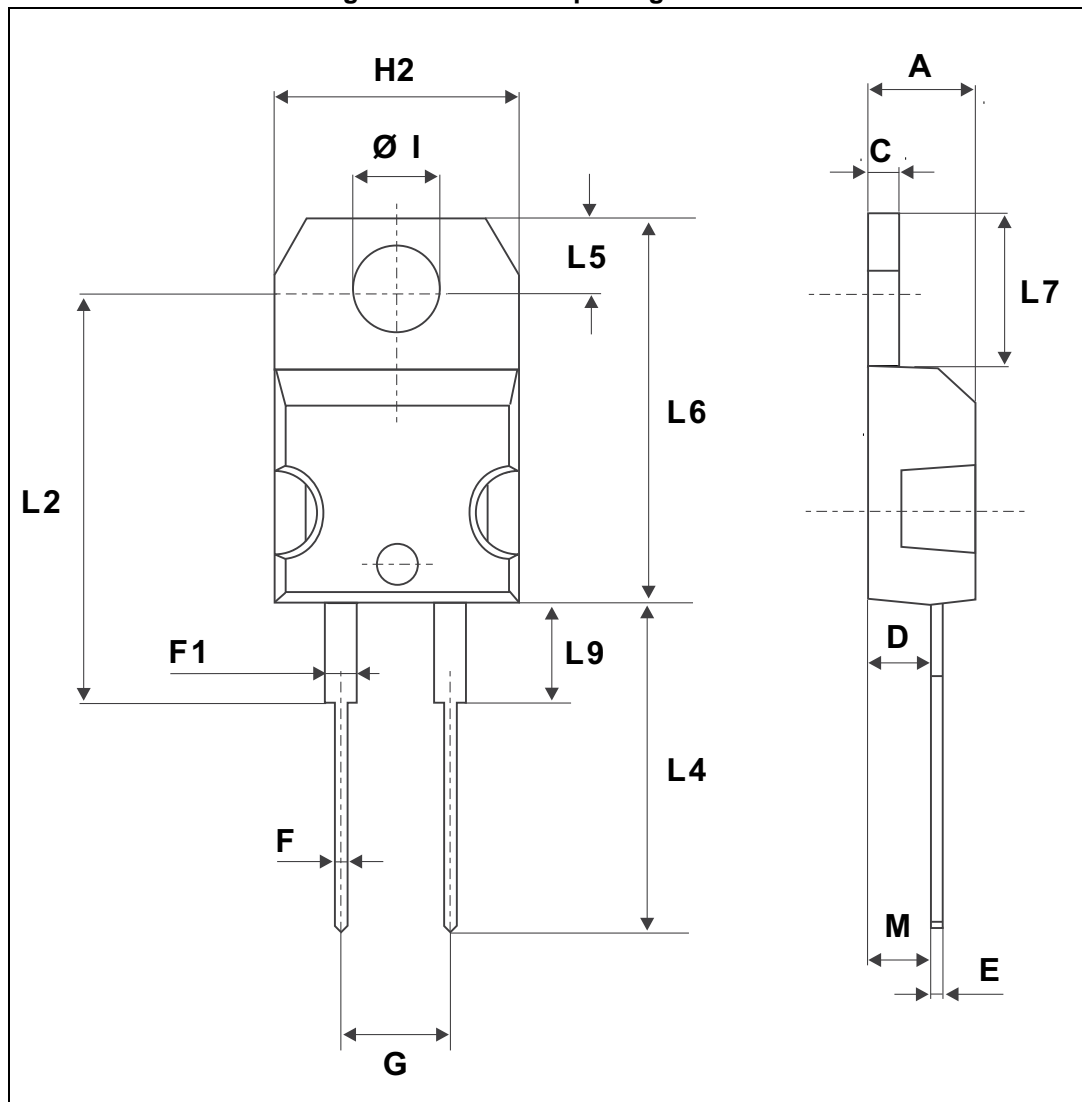


Table 6. TO-220AC package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

### 3 Ordering information

**Table 7. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPSC4C065D-L	PSC4C065D	TO-220AC	1.86 g	50	Tube

### 4 Revision history

**Table 8. Document revision history**

Date	Revision	Changes
18-May-2015	1	First issue.

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